

General Description

The CMD609 uses advanced trench technology MOSFETs to provide excellent RDS(ON) and low gate charge.

The complementary MOSFETs may be used in H-bridge, Inverters and other applications.

Features

- 40V 12A RDS(ON)≤21mΩ @ VGS=10V
RDS(ON)≤25mΩ @ VGS=4.5V
- -40V -12A RDS(ON)≤32mΩ @ VGS=10V
RDS(ON)≤40mΩ @ VGS=4.5V
- High Density Cell Design For Ultra Low On Resistance

Absolute Maximum Ratings

Symbol	Parameter	Max n-channel	Max p-channel	Units
V _{DS}	Drain-Source Voltage	40	-40	V
V _{GS}	Gate-Source Voltage	±20	±20	V
I _D @T _C =25°C	Continuous Drain Current	12	-12	A
I _{DM}	Pulsed Drain Current	36	-36	A
E _{AR}	Repetitive Avalanche Energy	9.8	20	mJ
P _D	Power Dissipation (T _C = 25°C)	27	30	W
T _{STG}	Storage Temperature Range	-55 to 175	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	-55 to 175	°C

Thermal Characteristics: n-channel

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Maximum Junction-to-Ambient	---	60	°C/W
R _{θJc}	Maximum Junction-to-Case	---	5.5	°C/W

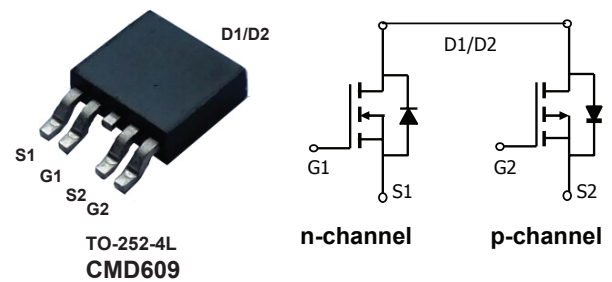
Product Summary

	BVDSS	RDS(ON)	ID
N-Channel	40V	21mΩ	12A
P-Channel	-40V	32mΩ	-12A

Applications

- Power Management
- Load Switch
- DC/DC Converter

TO-252-4L Pin Configuration



Thermal Characteristics: p-channel

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Maximum Junction-to-Ambient	---	60	$^{\circ}C/W$
$R_{\theta JC}$	Maximum Junction-to-Case	---	5	$^{\circ}C/W$

N Channel Electrical Characteristics ($T_J=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=12A$	---	---	21	m Ω
		$V_{GS}=4.5V, I_D=8A$	---	---	25	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1	---	2.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=40V, V_{GS}=0V$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=12A$	---	17	---	S
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	3	---	Ω
Q_g	Total Gate Charge (10V)	$V_{DS}=20V, V_{GS}=10V, I_D=12A$	---	8.5	---	nC
Q_{gs}	Gate-Source Charge		---	2.3	---	
Q_{gd}	Gate-Drain Charge		---	1.5	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DS}=20V, V_{GS}=10V, R_L=1.4\Omega$ $R_{GEN}=3\Omega,$	---	6.5	---	ns
T_r	Rise Time		---	4	---	
$T_{d(off)}$	Turn-Off Delay Time		---	16	---	
T_f	Fall Time		---	6.5	---	
C_{iss}	Input Capacitance	$V_{DS}=20V, V_{GS}=0V, f=1MHz$	---	1200	---	pF
C_{oss}	Output Capacitance		---	85	---	
C_{rss}	Reverse Transfer Capacitance		---	45	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V, \text{ Force Current}$	---	---	12	A
I_{SM}	Pulsed Source Current		---	---	36	A
t_{rr}	Body Diode Reverse Recovery Time	$I_F=12A, di/dt=100A/\mu s$	---	18	---	ns
Q_{rr}	Body Diode Reverse Recovery Charge		---	10	---	nC
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=1A$	---	---	1.2	V

P Channel Electrical Characteristics (T_J=25 °C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250μA	-40	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-10V , I _D =-12A	---	---	32	mΩ
		V _{GS} =-4.5V , I _D =-8A	---	---	40	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250μA	-1	---	-2	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-40V , V _{GS} =0V	---	---	-1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ±20V , V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =-5V , I _D =-12A	---	18	---	S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	---	16	---	Ω
Q _g	Total Gate Charge (10V)	V _{DS} =-20V , V _{GS} =-10V , I _D =-12A	---	16	---	nC
Q _{gs}	Gate-Source Charge		---	4	---	
Q _{gd}	Gate-Drain Charge		---	3.5	---	
T _{d(on)}	Turn-On Delay Time	V _{DS} =-20V , V _{GS} =-10V , R _L =1.4Ω R _{GEN} =3Ω ,	---	6.5	---	ns
T _r	Rise Time		---	8.5	---	
T _{d(off)}	Turn-Off Delay Time		---	45	---	
T _f	Fall Time		---	41	---	
C _{iss}	Input Capacitance	V _{DS} =-20V , V _{GS} =0V , f=1MHz	---	1300	---	pF
C _{oss}	Output Capacitance		---	100	---	
C _{riss}	Reverse Transfer Capacitance		---	70	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V , Force Current	---	---	-12	A
I _{SM}	Pulsed Source Current		---	---	-36	A
t _{rr}	Body Diode Reverse Recovery Time	I _F =-12A , di/dt=100A/μs	---	21	---	ns
Q _{rr}	Body Diode Reverse Recovery Charge		---	14	---	nC
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =-12A	---	---	1.5	V

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